



FOR IMMEDIATE RELEASE

Diodes, Inc. Launches New DFN Packaging Platform with Line of Ultra-Miniature Devices

Westlake Village, California -- April 21, 2005 – Diodes Incorporated, (Nasdaq: **DIOD**) a leading manufacturer and supplier of high quality discrete semiconductors, today announced the introduction of the first in a series of planned ultra-miniature discrete devices and arrays in the Company's new DFN Packaging Platform, employing an advanced leadless QFN (Quad Flat No-Lead) packaging technology.

The new QFN platform is an ideal choice for space-constrained applications such as mobile phones, PDAs, portable media and entertainment devices, digital cameras and camcorders, notebook computers, and wireless equipment. The leadless package design allows for the most efficient heat transfer, therefore offering one of the best power dissipation capabilities for a surface mount device.

Featuring one of the smallest footprints on the market, the new ultra-compact package requires only 40% of the PCB (Printed Circuit Board) area of the already sub-miniature SOD-523 package, while maintaining the power dissipation of packages such as SOT-23 that are nearly 10 times its size. Diodes, Inc. has introduced the DFN 1006-2 and DFN 1006-3, for two- and three-pin devices respectively, and plans to expand the range to include six- and eight-pin QFN platforms suitable for arrays in the future. The initial product offerings using the new ultra-compact micro-sized DFN package include four Schottky diodes and a Zener diode series from 5.6V to 24V. This will be followed by devices that include switching diodes and NPN/PNP transistors.

“QFN technology provides the flexibility for expanding pin counts as well as miniaturization of package size to meet customers' needs for specific array devices and mixed technology in discrete products without any sacrifice in performance,” said Mark King, Vice President of Sales and Marketing at Diodes, Inc. “By using this package, Diodes is able to offer our customers significant PCB real estate savings, while delivering greater value and much faster design and delivery cycles than can be achieved with monolithic chips in the QFN package. This exemplifies Diodes' ability to take the latest technology and drive it to scalable solutions suitable for high-volume end-market applications.”

The new DFN packages offer the highest power density over any SOD and SOT package at nearly 325mW/mm² (compared to 30mW/mm² for SOT-23 and 65mW/mm² for SOD-123). They feature a very low profile of only 0.53 mm in height (compared to 1.1 mm for SOT-23 and 1.35 mm for SOD-123) and an ultra compact footprint of 0.77 mm² of PCB area (compared to 9.9 mm² for SOT-23 and 7.6 mm² for SOD-123).

Diodes, Inc. plans to also extend this development effort to cover the SOD7xx series and SOD9xx series of micro size packages using the QFN platform.

For more information, visit <http://www.diodes.com> or contact Diodes' customer service at 805-446-4800 or email at info@diodes.com.

About Diodes Incorporated

Diodes Incorporated (Nasdaq: DIOD) is a leading manufacturer and supplier of high-quality discrete semiconductor products, serving the communications, computer, industrial, consumer electronics and automotive markets. The Company operates three Far East subsidiaries, Diodes-China (QS-9000 and ISO-14001 certified) in Shanghai, Diodes-Taiwan (ISO-9000 certified) in Taipei, and Diodes-Hong Kong. Diodes-China's manufacturing focus is on subminiature surface-mount devices destined for wireless devices, notebook, flat panel display, digital camera, mobile handset, set top box, DC to DC conversion, and automotive applications, among others. Diodes-Taiwan is our Asia-Pacific sales, logistics and distribution center. Diodes-Hong Kong covers sales warehouse and logistics functions. The Company's 5" wafer foundry, Diodes-FabTech (QS-9000 certified), specializes in Schottky products and is located just outside Kansas City, Missouri. The Company's ISO-9000 corporate sales, marketing, engineering and logistics headquarters is located in Southern California. For further information, visit the Company's website at <http://www.diodes.com>.

Safe Harbor Statement Under the Private Securities Litigation Reform Act of 1995: Any statements set forth above that are not historical facts are forward-looking statements that involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. Potential risks and uncertainties include, but are not limited to, such factors as fluctuations in product demand, the introduction of new products, the Company's ability to maintain customer and vendor relationships, technological advancements, impact of competitive products and pricing, growth in targeted markets, risks of foreign operations, and other information detailed from time to time in the Company's filings with the United States Securities and Exchange Commission.

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Recent news releases, annual reports, and SEC filings are available at the Company's website: <http://www.diodes.com>. Written requests may be sent directly to the Company, or they may be e-mailed to: diodes-fin@diodes.com.

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